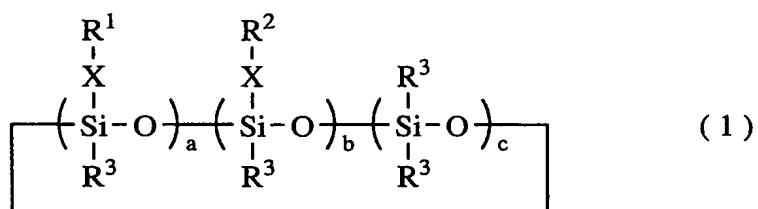


Amendments to the Claims

This listing of claims will replace all prior listings of claims in the application.

Listing of Claims

1. (Currently Amended) A thermal conductive silicone composition comprising 1 part by weight of a siloxane containing a hydrolytic group represented by the formula (1), based on 100 parts by weight of a base polymer having a curable functional group:



where; where

R¹÷R¹ is a group containing an alkoxysiloxylalkoxysilyl group having 1 to 4 carbon atoms;

R²÷R² is a siloxanesiloxyl group represented by the following formula (2) or a monovalent hydrocarbon group having 6 to 18 carbon atoms;

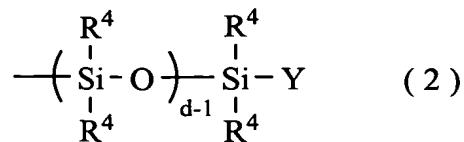
X÷X is a divalent hydrocarbon group having 2 to 10 carbon atoms;

a and b÷b are integers of 1 or more;

e÷c is an integer of 0 or more;

the sum of a + b + e÷c is an integer of 4 or more;

R³÷R³ is a monovalent hydrocarbon group having 1 to 6 carbon atoms or a hydrogen atom, provided that R³seach R³ may be the same as or different from each other;



R⁴ is a monovalent hydrocarbon group having 1 to 12 carbon atoms;

Y is a group selected from a methyl group, a vinyl group and R¹; and

d is an integer of 2 to 500.

2. (Canceled)

3. (Currently Amended) The composition of ~~Claim 2, the composition~~ Claim 1, further comprising a thermal conductive filler in an amount of 10 to 3000 parts by weight based on a total of 100 parts by weight of the hydrolytic group-containing siloxane and the base polymer having the curable functional group.

4. (Currently Amended) The composition of Claim 3, wherein the thermal conductive filler is selected from alumina, magnesium oxide, boron nitride, aluminum nitride, silica powder, metal powder, diamond, aluminum hydroxide and, carbon and surface-treated products of these compounds.

5. (Previously Presented) The composition of Claim 1, wherein the thermal conductive silicone composition is an addition reaction-curable type.